Heat transfer from an ultrafast laser heated metal film to a substrate

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Introduction 1

$\mathbf{2}$ Classical Treatment

2.1 Perfect thermal contact

These results are taken from Example 10.8 of Hahn and Ozisik, Heat Conduction (Wiley, 2012). The consider a two-layer composite slab with one semi-infinite layer as shown in Fig. XXX. We will identify the film as region 1 and the bulk as region 2. The layers are presumed to be in perfect thermal contact with region 1 initially at a uniform temperature T_0 and region 2 at zero temperature. Define a dimensionless temperature $\theta_i(x,t)$ as

$$\theta_i(x,t) = \frac{T_i(x,t)}{T_0} \qquad i = 1,2 \tag{1}$$

With this transformation, the heat transfer problem is written

$$\frac{\partial^2 \theta_1}{\partial x^2} = \frac{1}{\alpha_1} \frac{\partial \theta_1}{\partial t} \qquad in \qquad 0 < x < L, \ t > 0$$
 (2a)

$$\frac{\partial^2 \theta_1}{\partial x^2} = \frac{1}{\alpha_1} \frac{\partial \theta_1}{\partial t} \qquad in \qquad 0 < x < L, \ t > 0
\frac{\partial^2 \theta_2}{\partial x^2} = \frac{1}{\alpha_2} \frac{\partial \theta_2}{\partial t} \qquad in \qquad x > L, \ t > 0$$
(2a)

subject to the boundary conditions

$$\left. \frac{\partial \theta_1}{\partial x} \right|_{x=0} = 0 \tag{3a}$$

$$\theta_1(x = L, t) = \theta_2(x = L, t) \tag{3b}$$

$$k_1 \frac{\partial \theta_1}{\partial x}\Big|_{x=L} = k_2 \frac{\partial \theta_2}{\partial x}\Big|_{x=L}$$
 (3c)

$$\theta_2(x \to \infty, t) \to 0$$
 (3d)

and the initial conditions

$$\theta_1(x, t = 0) = 1$$
 in $0 < x < L$ (4a)

$$\theta_2(x, t = 0) = 0$$
 in $L < x < \infty$ (4b)

where k_i are the thermal conductivities and α_i are the thermal diffusivities of region 1 (film) and region 2 (bulk). Using Laplace rransforms, the solution for the temperature distribution in the two-layer medium is

$$\frac{T_1(x,t)}{T_0} = 1 - \frac{1+\gamma}{2} \sum_{n=0}^{\infty} \gamma^n \left\{ \operatorname{erfc}\left[\frac{(2n+1)L - x}{2\sqrt{\alpha_1 t}}\right] + \operatorname{erfc}\left[\frac{(2n+1)L - x}{2\sqrt{\alpha_1 t}}\right] \right\}$$
 (5a)

$$\frac{T_2(x,t)}{T_0} = \frac{1+\gamma}{2} \sum_{n=0}^{\infty} \gamma^n \left\{ \operatorname{erfc} \left[\frac{(2nL+\mu(x-L))}{2\sqrt{\alpha_1 t}} \right] - \operatorname{erfc} \left[\frac{(2n+2)L+\mu(x-L)}{2\sqrt{\alpha_1 t}} \right] \right\}$$
 (5b)

where the unitless parameters μ and γ are defined by

$$\mu = \sqrt{\frac{\alpha_1}{\alpha_2}} \tag{6a}$$

$$\beta = \frac{k_1}{k_2} \frac{1}{\mu} \tag{6b}$$

$$\gamma = \frac{\beta - 1}{\beta + 1}.\tag{6c}$$

- 2.2 Examples of the classical heat conduction result
- 2.2.1 Aluminum on Silicon
- 2.2.2 Aluminum on Gallium Arsenide
- 2.2.3 Aluminum on Germanium
- 2.2.4 Aluminum on Indium Antimonide
- 2.3 Diffusive Mismatch Correction
- 2.4 Acoustic Mismatch Correction

3 Microscopic Treatment

Consider the same problem as in the previous section, but determine the second order energy correction. You may leave your answer in the form of a summation.

Appendix: Parameters

Appendix: Code

The most recent and up to date code should be obtained from https://github.com/elandahl/dynamical-diffraction/tree/TRXD/strain_functions. This code listing is for reference only.

```
% thermalFilm.m
% Classical strain model for a thin Aluminum film on a semiconductor
% Presumes that the temperature rise on the film is uniform and instantaneous
% and that the thermal contact is perfect
% A more sophisticated model with better Physics (e.g. AMM, DMM) will be needed!
% Also, does not include nanoscale phenomena (e.g. phonon mean free path)
% Also, no acoustic propogation is included. This could be called later.
% Model: see p. 429 (Sec. 10.7) of Hahn, "Heat Conduction" 3rd edition
% Aluminum properties are hard coded
% Semiconductor properties looked up in sample.dat, which is required
% First written by Eric Landahl, 12.28.2016
% Revised by EL 1.9.2017
% Usually called by TRXD.m
%
%% INPUTS:
%
   crystal
                determines x-ray and strain properties, chosen from:
%
      GaAs
%
      Si
%
      Ge
%
      InSb
%
   fluence
                absorbed laser fluence in mJ/cm<sup>2</sup>
%
                a vector of times to be calculated in seconds
   time
                usually 5*Lext, Lext is the x-ray extinction length in meters
%
   max_depth
%% OUTPUTS:
   longitudinal
                    longitudinal strain, size = length(time_out) x length(z)
%
   transverse
                    transverse strain, size = length(time_out) x length(z)
%
                    sheer strain, size = length(time_out) x length(z)
  sheer
%
                    a vector of depths in meters
%
   time_out
                    a vector of times returned in seconds, not the same as time_in
%% NOTE: The strain will be calculated out to time_in(end) however the time-steps
%
         are chosen for convenience and accuracy in evaluating the strain.
%
         time_in is NOT usually equal to time_out
         therefore the strain must be interpolated temporally after calling this
%
%
         function
%
WW NOTE ALSO: Three strain components are returned, but usually only longitudinal
%
              is non-zeros
%
%% TYPICAL USAGE
```

```
% [st1 st2 st3 time_out z] = thermalFilm ('Si', 1, (1e-10:2e-10:1e-8), 1e-5);
function [longitudinal trans sheer time_out z]=thermalFilm(crystal,fluence,time_in,max_depth)
% Remesh time
 time = time_in;
 % In this simple model, there is no penalty for calculating many timepoints
 % so the given array of timepoints is used.
% Aluminum film properties. "1" refers to the film
 L = 70e-9; % Film thickness in m
 C1 = 904; %Specific heat of film in J/(kg K)
 rho1 = 2712; % Film density in kg/m<sup>3</sup>
 k1 = 204; % Film thermal conductivity in W/(m K)
  alpha1 = 8.418E-5; % Film thermal diffusivity in m^2/s
% Load substrate properties. "2" referes to the substrate
  load sample.dat;
  ID = find(strcmp({sample.name}, crystal)==1);
  alpha_t = sample(ID).thermalExpansion.val; % 1/K
  alpha2 = sample(ID).thermalDiffusion.val; % cm^2/s
  alpha2 = alpha2 / 10000; % convert from cm^2/s to m^2/s
 k2 = sample(ID).thermalConductivity.val; % W/(cm K)
 k2 = k2 * 100; % Convert from W/(cm K) to W/(m K)
 C2 = sample(ID).specificHeat.val; % J/(g K)
 C2 = C2 * 1000; % Convert from J/(g K) to J/(kg K)
 rho2 = sample(ID).massDensity.val; % g/cm^3
 rho2 = rho2 * 1000; % Convert from g/cm^3 to kg/m^3
 "" Temporary for troubleshooting: make the sampe all semiconductor
% rho1 = rho2;
% k1 = k2;
% C1 = C2;
% Calculate initial temperature rise
  fluence = fluence*10; % Convert from mJ/cm^2 to J/m^2
 TO = fluence/(L * C1 * rho1); % Initial temperature rise in film
 fprintf('A %d nm thick Aluminum film gives a temperature rise of %.1f K.\n',L*1e9,T0)
% Unitless parameters (see Hahn, "Thermal Conductivity", Eqs. 10-135 and 10-138)
 mu = sqrt(alpha1/alpha2);
  beta = (k1/k2)/mu;
 gamma = (beta - 1)/(beta + 1);
% Spatial grid
 num_depths = 10000; % number of depth points z to be calculated
 dz = max_depth/num_depths;
```

```
z = dz:dz:max_depth;
% Meshgrid for calculation speed & ease
  [Time Z] = meshgrid(time,z); % Time and Z are 2D, time and z are 1D
% Calculate temperature profile in bulk
 max_n = 100; % number of terms in series expansion, default 100
 T2a = 0.*Time.*Z; % each term gets added to this, starts at zero
 for n = 0: max_n % Series expansion solution of heat equation
    T2b = erfc((2*n*L + mu*Z)./(2*(sqrt(alpha1*Time)))); % temporary
    T2c = erfc(((2*n + 2)*L + mu*Z)./(2*sqrt(alpha1*Time))); % temporary
    T2a = T2a + (gamma^n) * (T2b - T2c); % temporary, adding up
 T2 = T0 * (1/2) * (1 + gamma) * T2a; % Temperature at all z and time
% Film calculations are not needed except to check conservation of energy
% Calculate temperature profile in film. zz and ZZ are the film depths
  dzz = L/100; % Choose 100 depth points in the film by default
  zz = dzz:dzz:L;
  [Time ZZ] = meshgrid(time,zz);
 T1a = 0.*Time.*ZZ;
  for n = 0:max_n
    T1b = \operatorname{erfc}(((2*n + 1)*L - ZZ)./(2*\operatorname{sqrt}(\operatorname{alpha1*Time})));
    T1c = erfc(((2*n + 1)*L + ZZ)./(2*sqrt(alpha1*Time)));
    T1a = T1a + (gamma^n) * (T1b + T1c);
  end
 T1 = T0 - T0 * (1/2) * (1 - gamma) * T1a; % Temperature in film
 T1_end = mean(T1(:,end)); % Average temperature at final timepoint
  fprintf('After %.1f ns, the average film temperature rise is only %.1f deg C.\n', ...
  time(end)*1e9,T1_end);
  fprintf('The maximum bulk %s temperature rise is %.1f deg C.\n',crystal, ...
 max(max(T2)));
% Calculate heat in film
% Q = integral dzz of rho*C*T
% Q1 = trapz(ZZ,T1*rho1*C1);
% Q2 = trapz(Z,T2*rho2*C2);
% Q1 = Q1/10; % convert from J/m^2 to mJ/cm^2
\% Q2 = Q2/10; \% convert from J/m<sup>2</sup> to mJ/cm<sup>2</sup>
% Calculate strains in bulk
  longitudinal = alpha_t.*T2'; % Strain is thermal expansion coeff times temperature
  trans =0.*T2'; % No transverse strain
  sheer = 0.*T2'; % No sheer strain
  time_out = time;
% Outputs not needed for TRXD
```

save thermal FilmOut.m; $\mbox{\ensuremath{\%}}$ Save all variables for future use end